

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	62	(pressure sensor) and chip and (substrate or support) and (bond Wire) and @ad<"20030227"	US-PGPUB; USPAT; EPO; JPO; DERWE NT; IBM_T DB	2005/05/10 10:03
2	BRS	L2	7	1 and au and pd	US-PGPUB; USPAT; EPO; JPO; DERWE NT; IBM_T DB	2005/05/10 10:06
3	BRS	L3	171	(bond wire) and au and pd	US-PGPUB; USPAT; EPO; JPO; DERWE NT; IBM_T DB	2005/05/10 10:06
4	BRS	L4	144	3 and @ad<"20030227"	US-PGPUB; USPAT; EPO; JPO; DERWE NT; IBM_T DB	2005/05/10 10:10

	Type	L #	Hits	Search Text	DBs	Time Stamp
5	BRS	L5	9	((bond wire) same (au and pd)) and @ad<"200300227"	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/05/1 0 10:12
6	BRS	L6	0	(au/pd bond wire) and @ad<"200300227"	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/05/1 0 10:21
7	BRS	L7	2	(au/pd wire) and @ad<"200300227"	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/05/1 0 10:22
8	BRS	L8	148	(au pd alloy) and @ad<"200300227"	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/05/1 0 10:22

	Type	L #	Hits	Search Text	DBs	Time Stamp
9	BRS	L9	570	(pressure sensor) and (circuit chip) and @ad<"20030227"	US-PGPUB; USPAT; EPO; JPO; DERWE NT; IBM_T DB	2005/05/10 11:34